Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**PAD FUNCTIONS:**

1. **1A**
2. **1B**
3. **1Y**
4. **2A**
5. **2B**
6. **2Y**
7. **GND**
8. **3Y**
9. **3A**
10. **3B**
11. **4Y**
12. **4A**
13. **4B**
14. **VCC**

**.052”**

**.049”**

**2 1 14 13 12**

**5 6 7 8 9**

**3**

**4**

**11**

**10**

**MASK**

**REF**

**HCT132T**

**Top Material: Al**

**Backside Material: Si Ni**

**Bond Pad Size: .0033” X .0033”**

**Backside Potential: VCC (can leave FLOATING)**

**Mask Ref: HCT132T**

**APPROVED BY: DK DIE SIZE .049” X .052” DATE: 8/30/21**

**MFG: TEXAS INSTRUMENTS THICKNESS .025” P/N: 54HCT132**

**DG 10.1.2**

#### Rev B, 7/19/02